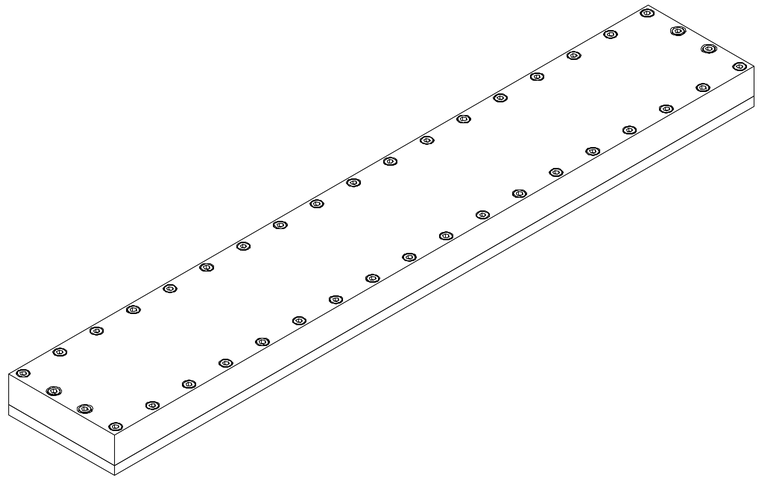
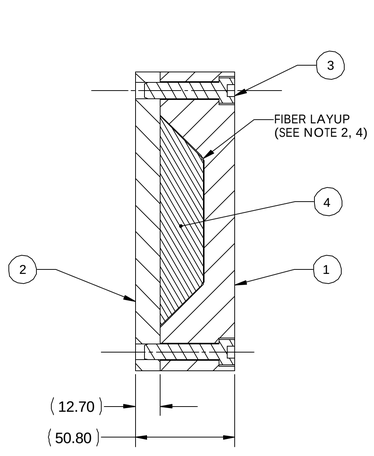
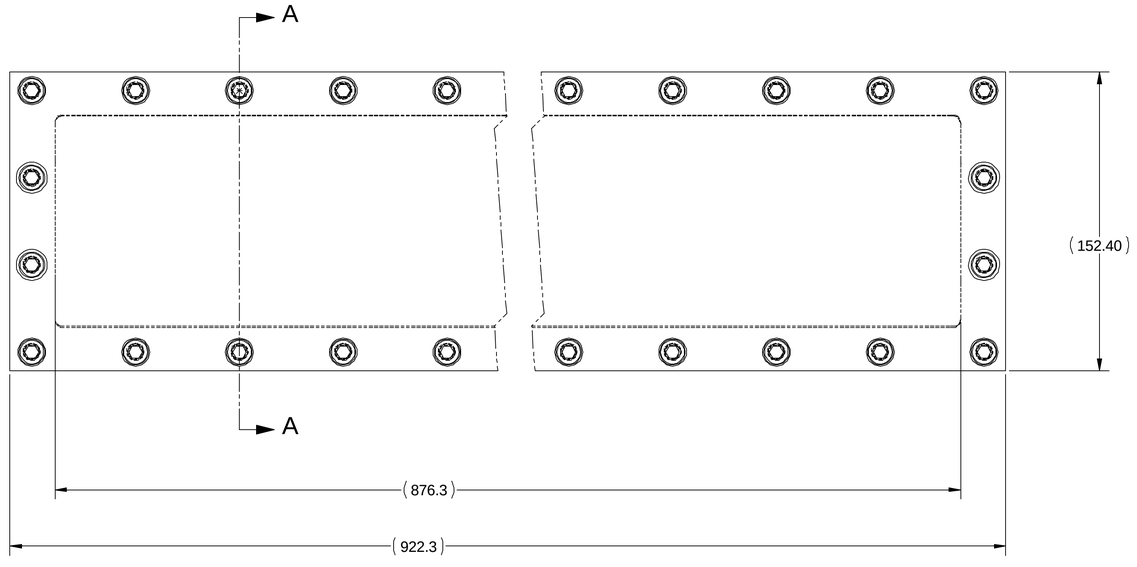
DWG. NO.	SIZE	REV.	SH.
21F705 4		-	1

ITEM	PART NO.	REQD	DESCRIPTION	MATERIAL
4		1	INNER VERTEX STIFFENER SILICONE MOLD INSERT	
3		40	M8.0 X 1.25 SOCKET HD CAP X 38.1	STEEL
2	21F707	1	MOLD COVERPLATE	
1	21F706	1	PANEL INNER CORNER MOLD CAVITY	





SECTION A-A



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS IN MILLIMETERS
2. ASSEMBLY USED TO MOLD THE INNER CORNERS FOR SPACEFRAME CENTRAL AND END SECTION (PARTS 21F655 AND 21F671)
3. ASSEMBLY WEIGHS 100 Lbs.
4. SEE PART DRAWINGS FOR MATERIAL SPECIFICATIONS

REV	DWG	CHK	ZONE	DATE	CHANGES

UNLESS OTHERWISE SPECIFIED

TOLERANCES:
X.X ± 0.5 FRAC. ± 1/64
X.XX ± 0.25 ANGLES ± 30'
X.XXX± 0.013 FINISH 1.6

DO NOT SCALE PRINT

THREADS ARE CLASS 2
CHAMFER ENDS OF ALL SCREW THREADS 30°
CUT ROUND, 1.5 THREAD RELIEF ON MACHINED THREADS
BREAK EDGES .016 MAX. ON MACHINED WORK
REMOVE BURRS, WELD SPLATTER & LOOSE SCALE
IN ACCORDANCE WITH ASME Y14.5m & B46.1

SHOP ORDERS

ACCT NO.	NO. REQD
DEL TO	
SURFACE TREATMENT	
IDEN METHOD TAG	
PROJECT NUMBER	ATL-IP-ED-XXXX
PROJECT NAME	US ATLAS SILICON SUBSYSTEM
DWG BY	W. K. MILLER — DATE 4/16/2002
CHK BY	BILL WILDS — DATE 4/16/2002
APR BY	E. ANDERSSEN — DATE 4/16/2002

SER NO.
DATE ISSD
DATE REQD
US ATLAS SILICON SUBSYSTEM (USSS)

ERNEST ORLANDO LAWRENCE
BERKELEY NATIONAL LABORATORY
UNIVERSITY OF CALIFORNIA - BERKELEY

ATLAS PIXEL DETECTOR
SPACEFRAME CENTRAL AND END SECTION
PANEL INNER CORNER MOLD ASSEMBLY

MICROFILMED:	DWG. TYPE	SHOWN ON	SCALE: 1:1.5	DO NOT SCALE PRINTS
	ASSEM	N/A	SHEET 1 OF 1	
PATENT CLEAR:	DESIGN ACCT. NO.	CATEGORY CIDE	DWG. NO. 21F705 4	SIZE - REV. -
	P1AP-11	AP6250		